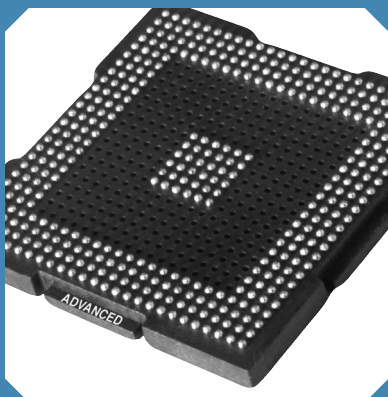


BGA Adapter Sockets



Features:

- Advanced® exclusive solder ball terminals offer superior SMT processing.
- Same footprint as BGA device.
- Proven long-term performance in vigorous temperature cycling applications - solder ball terminal absorbs TCE mismatch.
- Closed bottom socket terminal for 100% anti-wicking of solder.
- Gold contacts allow gold/gold interconnections to Adapter pins.
- Low insertion force socket with multi-fingered high reliability Beryllium Copper contacts.
- Coplanarity consistently under .006 inch industry standard.
- Custom designs available.

Specifications:

Terminals:

Brass - Copper Alloy
(C36000) ASTM-B-16

Contacts:

Beryllium Copper
(C17200) ASTM-B-194

Solder Ball:

Standard: 63Sn/37Pb
Lead-free: 95.5Sn/4.0Ag/0.5Cu

Plating:

G - Gold over Nickel
Gold per ASTM-B-488
Nickel per QQ-N-290

Ball Grid Array (BGA) Adapter Sockets

For use with BGA Adapters on pages 6-7

Table of Models

	Description: Standard Socket (S) Mat'l: High Temp. Liquid Crystal Polymer (LCP)* Index: -60°C to 260°C (-76°F to 500°F)	Insulator Size: Same size as BGA device body
	Description: Extraction Socket (SB) Mat'l: High Temp. Liquid Crystal Polymer (LCP)* Index: -60°C to 260°C (-76°F to 500°F)	Insulator Size: 1.27mm Pitch: BGA device body +.079/(2.00) 1.00mm Pitch: BGA device body +.138/(3.50)

RGS/RGSB replaces MGS/MGSB, MHS/MHSB replaces FHS/FHSB.

* Some sizes may only be available in FR-4. See How To Order section or consult factory.

Options



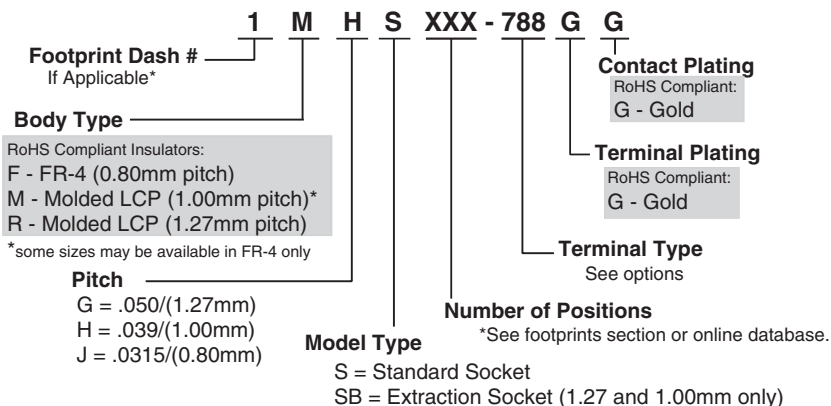
Tape and Reel Packaging

- Conforms to EIA-481 Standard.
- Pick-up tape included.
- Add -TR to end of part number when ordering.
- Custom packaging available
- If -TR is not specified, standard tray packs are used.



- Extraction tool (P/N 8125) is available separately.
- Works with Extraction Slot Adapters and LCP or FR-4 sockets.

How To Order



Tel. 0 89 / 158 126-0

Internet: <http://www.infratron.de>

e-mail: info@infratron.de

Note: See pages 4-5 for 0.50mm and 0.65mm pitch.

Ball Grid Array (BGA) Adapter Sockets

For use with BGA Adapters on pages 6-7

Additional standard and custom terminals available.
See Terminals section or consult factory.

Standard Terminals

SMT (Surface Mount)

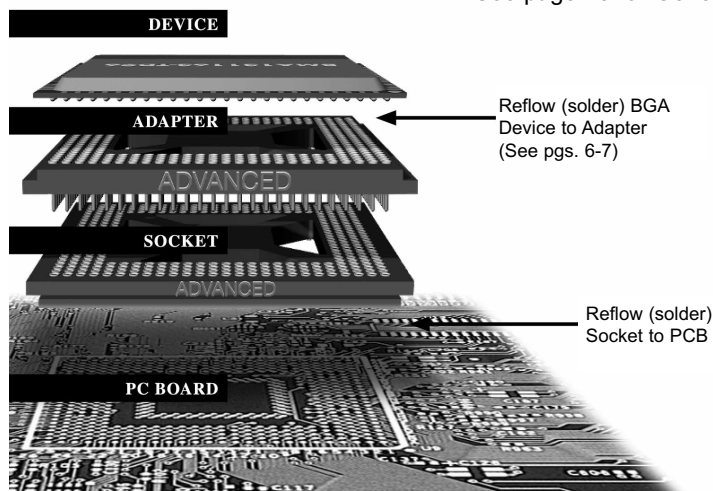
Tin/Lead: Type -636 Lead-free: Type -819 1.27mm pitch PATENTED	Tin/Lead: Type -790 Lead-free: Type -788 1.00mm pitch PATENTED	Tin/Lead: Type -702 Lead-free: Type -828 0.80mm pitch PATENTED
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Thru-Hole

Type -673 1.27mm pitch PATENTED	Type -789 1.00mm pitch PATENTED	Type -731 0.80mm pitch PATENTED
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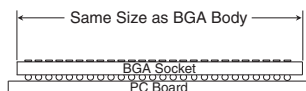
How It Works

See page 15 for Generic Reflow Profiles.



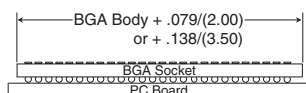
- Either Tin/Lead or Lead-free device packages can be attached to our RoHS Compliant Adapters.
- PC boards can be processed with Tin/Lead BGA sockets in standard profiles or lead-free BGA sockets in RoHS Compliant, high temperature profiles.

Dimensional Information



Standard Socket (S)

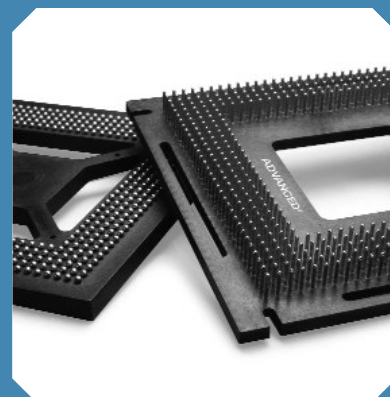
- Mates with Standard Adapter (A)
- Socket size same as BGA device body
- Use with SMT Adapter for LGA and reworked BGA device socketing (or board to board applications)



Extraction Socket (SB)

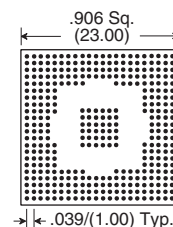
- Mates with Extraction Slot Adapter (AX)
- Socket size equals BGA body + .079/(2.00) for 1.27mm pitch or BGA body + .138/(3.50) for 1.00mm pitch
- Protects valuable PCB during device/adapter extraction - tool never touches PCB
- Available in 1.00 and 1.27mm pitch only

BGA Adapter Sockets



Footprints:

360 Pins
Footprint Number 360-2



22 x 22 rows

- Full grid molded insulators populated to exact device pattern.
- Over 1000 footprints available - see page 88, search online or submit your device specs.
- Use our Build-A-Part feature or search in our online BGA Socket Finder™ at www.bgasockets.com.

Available Online:

- RoHS Qualification Test Report
- Technical articles
- Test data
- Signal Integrity Performance
- CAD drawings
- Generic Tin/Lead and Lead-free Reflow Profiles



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